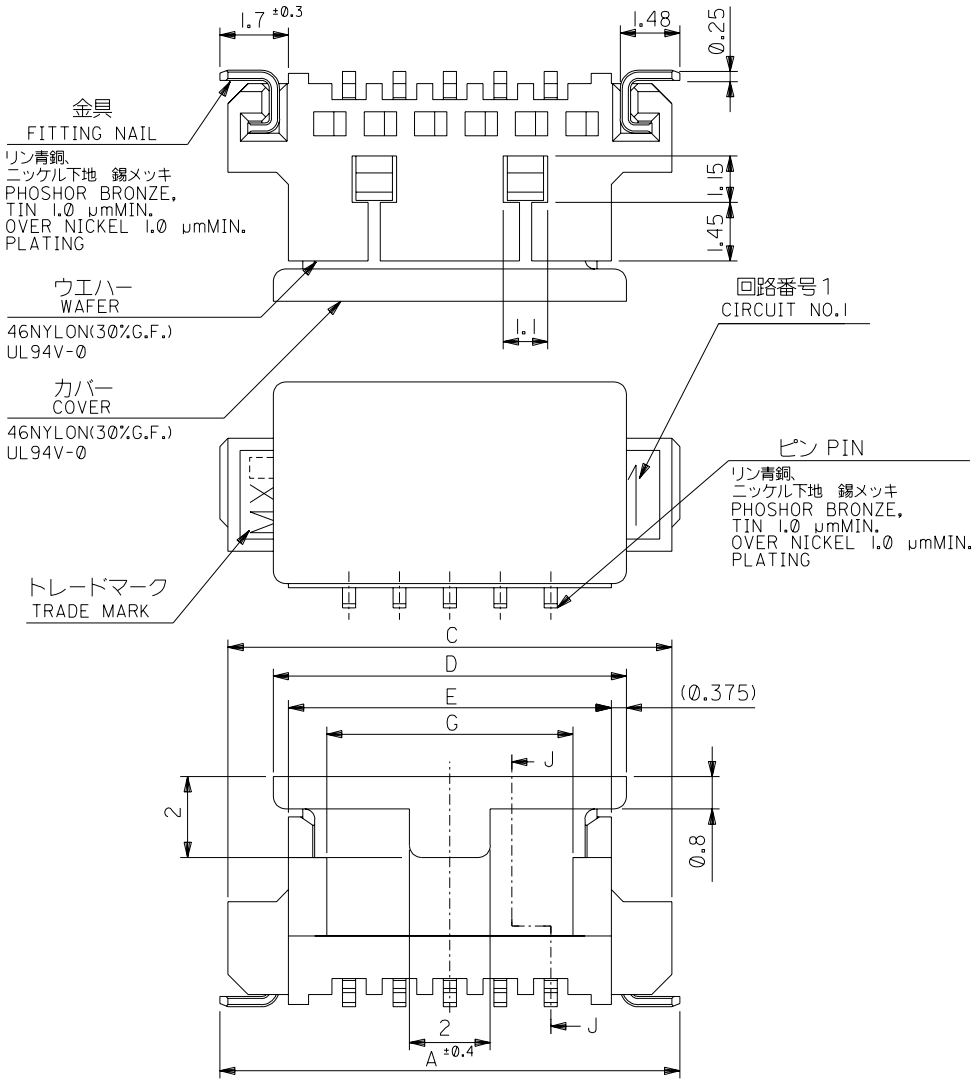
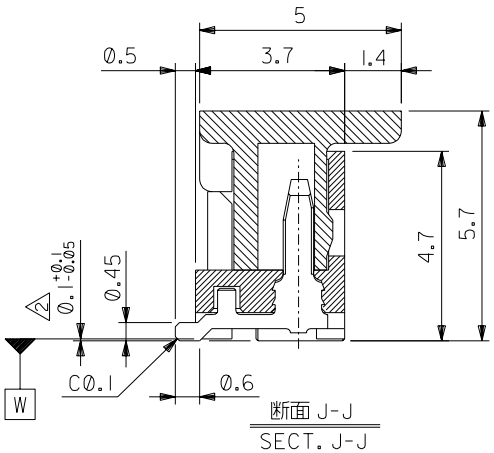
DWG. NO. SD-53398-034



NOTES

1. 嵌合相手：51021シリーズ MATE WITH : 51021 SERIES
2. 水平面上においての、ウエハー底面 [W] とソルダーテール及び フィッティングネイル底面とのズレ量を示す。 MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM [W]
3. 偶数極にのみ適用。APPLY EVEN CIRCUIT PRODUCTS.
4. 本製品は 53398-**20 の鉛フリー品である。 THIS PRODUCT IS LEAD FREE OF 53398-**20.



17.35	18.05	19.25	20	22.25	16.25	22.3	53398-1429	14
14.85	15.55	16.75	17.5	19.75	13.75	20.15	53398-1229	12
9.85	10.55	11.75	12.5	14.75	8.75	15.15	53398-0829	8
8.6	9.3	10.5	11.25	13.5	7.5	13.9	53398-0729	7
7.35	8.05	9.25	10	12.25	6.25	12.65	53398-0629	6
6.1	6.8	8	8.75	11	5	11.4	53398-0529	5
4.85	5.55	6.75	7.5	9.75	3.75	10.15	53398-0429	4
3.6	4.3	5.5	6.25	8.5	2.5	8.9	53398-0329	3
2.35	3.05	4.25	5	7.25	1.25	7.65	53398-0229	2
G	F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

DO NOT SCALE DRAWING

	EC NO.	DRWN:	CH'K:	APPR:
	EC NO.	DRWN:	CH'K:	APPR:
	EC NO.	DRWN:	CH'K:	APPR:
	EC NO.	DRWN:	CH'K:	APPR:
DESCRIPTION	RELEASED '04/02/12	EC NO. J2004-2404	DRWN: Y.SAKIYAMA	CH'K: M.SASAO	APPR: M.SASAO
REV	Ø				

MATERIAL 材料: SEE DRAWING

FINISH 仕上げ

WIRE RANGE 適用電線範囲

INS. RANGE 被覆外径

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	
10 UNDER 未満	±0.2
10 OVER 以上 30 UNDER 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

MODEL NO. 53398-**29

SCALE —

DESIGN UNITS ☒mm ☐INCH

THIRD ANGLE PROJECTION

DIMENSIONS: ☐ mm/INCH ☐ INCH/mm ☒ mm ONLY

SHT REV

REVISE ON CAD ONLY

DRAWN BY & DATE Y.SAKIYAMA '04/02/12

CHECKED BY & DATE M.SASAO '04/02/12

APPROVED BY & DATE M.SASAO '04/02/12

TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-

molex MOLEX INCORPORATED

CAD FILENAME SD-53398-034.S01

MATERIAL NO. SEE CHART

DRAWING NO. SD-53398-034

SHEET NO. 1 OF 2

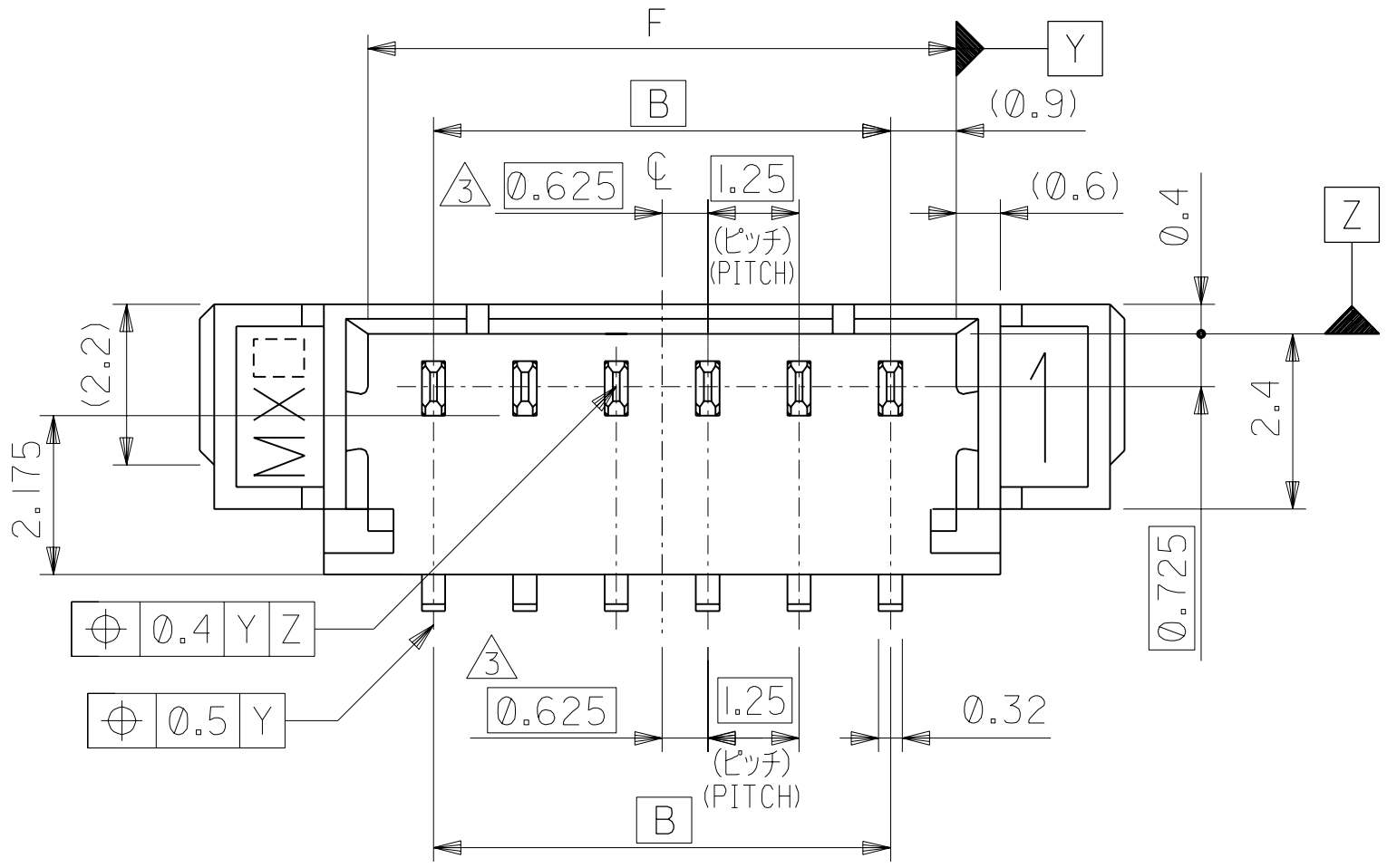
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

SIZE B

SD-53398-034.S01 A

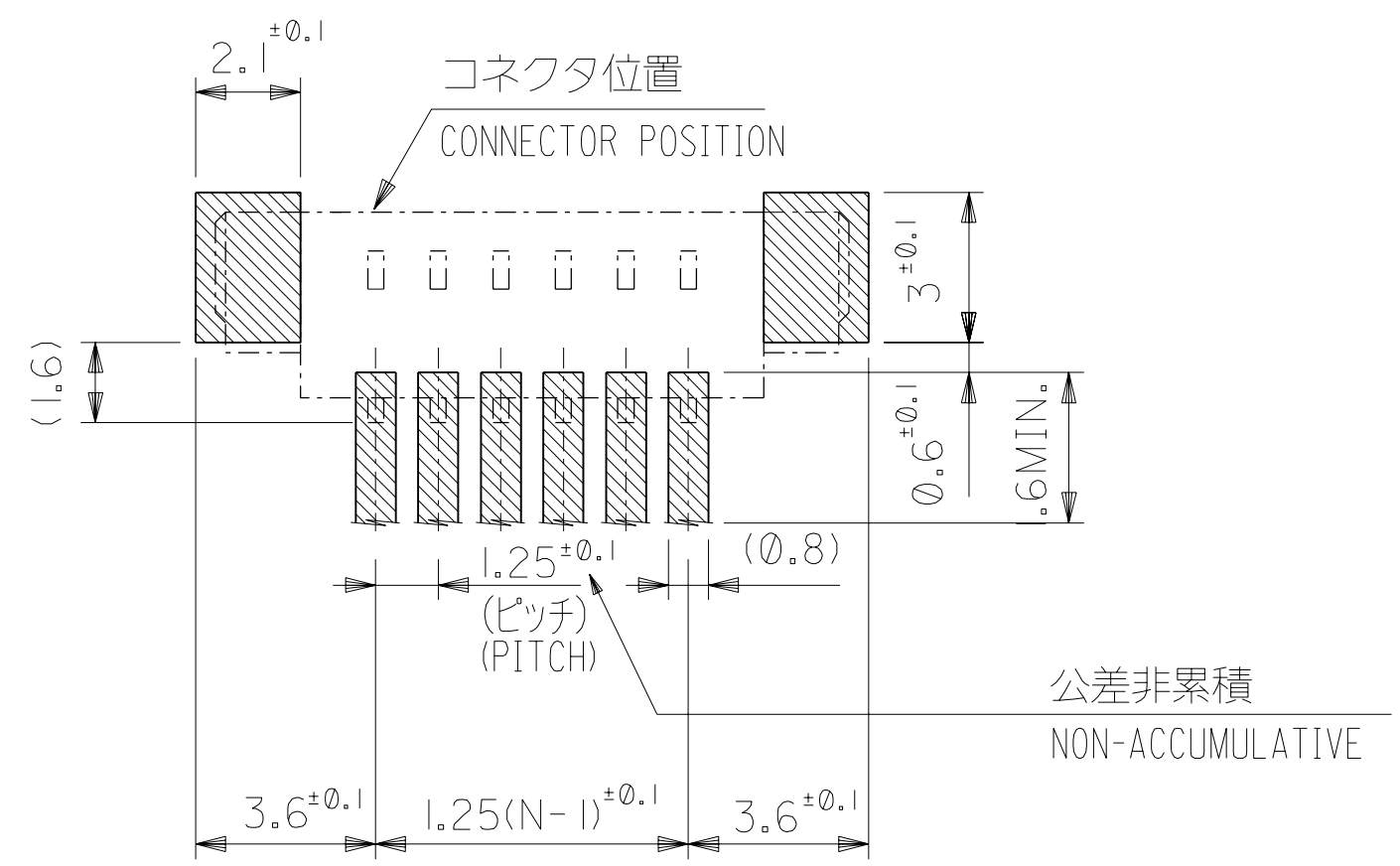
EN-02J(097) MXJ-54

DWG. NO. SD-53398-034



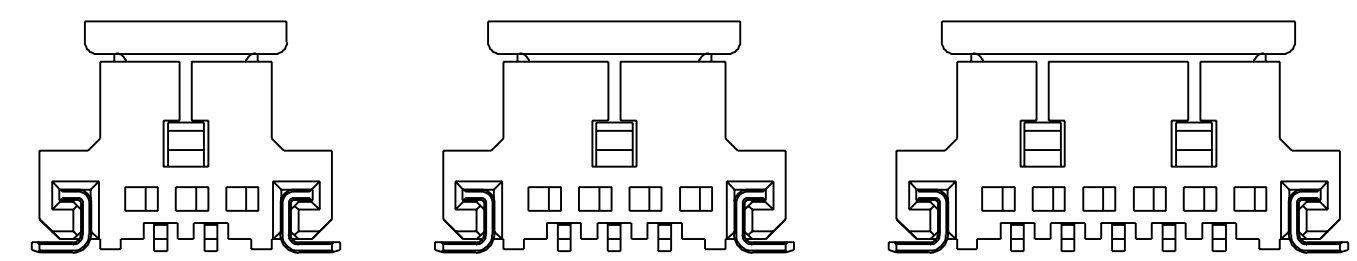
カバーなしの場合 (53398-**19)

IN CASE OF WITHOUT COVER



参考基板レイアウト

RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)



2極
2 CKT.

3極
3 CKT.

4極以上
OVER 4 CKT.

5 ロック形状図

LOCK CONFIGURATION

NOTES

5 ロック窓は、2，3極は1ケ所、4極以上は2ケ所とする。
LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS.
TWO PLACES FOR MORE THAN 4 CKTS.

MODEL NO.	53398-**29
DIMENSIONS:	mm/INCH, INCH/mm, ☒ mm ONLY
SHT	REV
REVISE ON CAD ONLY	
SCALE	—/—
DESIGN UNITS	☒mm ☐INCH
THIRD ANGLE PROJECTION	
MATERIAL 材料	SEE NOTES
FINISH 仕上げ	—/—
WIRE RANGE 適用電線範囲	—/—
INS. RANGE 被覆外径	—/—
GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	
10 UNDER 未満	±0.2
10 OVER 以上 30 UNDER 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°
DRAWN BY & DATE	Y.SAKIYAMA '04/02/12
CHECKED BY & DATE	M.SASAO '04/02/12
APPROVED BY & DATE	M.SASAO '04/02/12
CAD FILENAME	SD-53398-034.S02
TITLE:	1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT (ST.) WITH COVER -LEAD FREE-
	MOLEX INCORPORATED
MATERIAL NO.	SEE CHART
DRAWING NO.	SD-53398-034
SHEET NO.	2 OF 2
SIZE	B

REV	DESCRIPTION
0	RELEASED '04/02/12 EC NO. J2004-2404 DRWN: Y.SAKIYAMA CH'K: M.SASAO APPR: M.SASAO

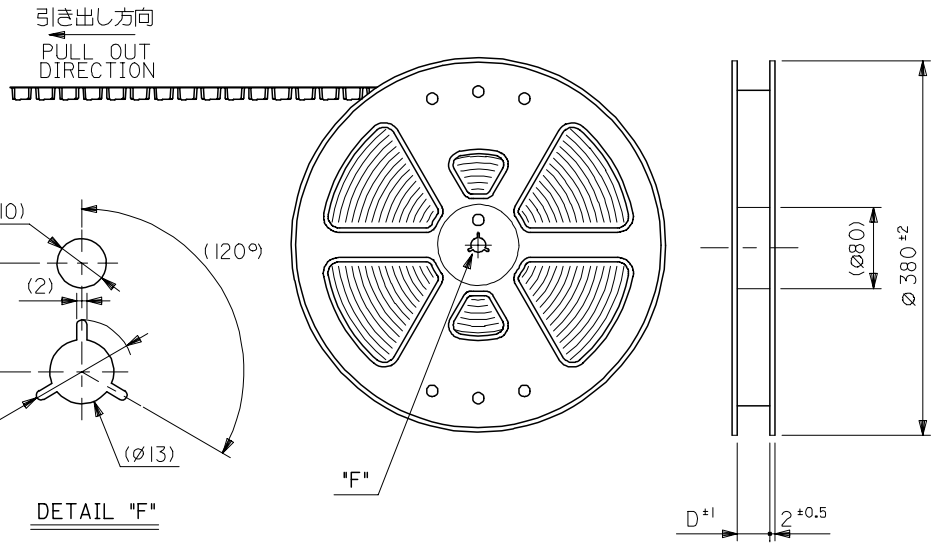
EC NO. DRWN: CH'K: APPR:

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

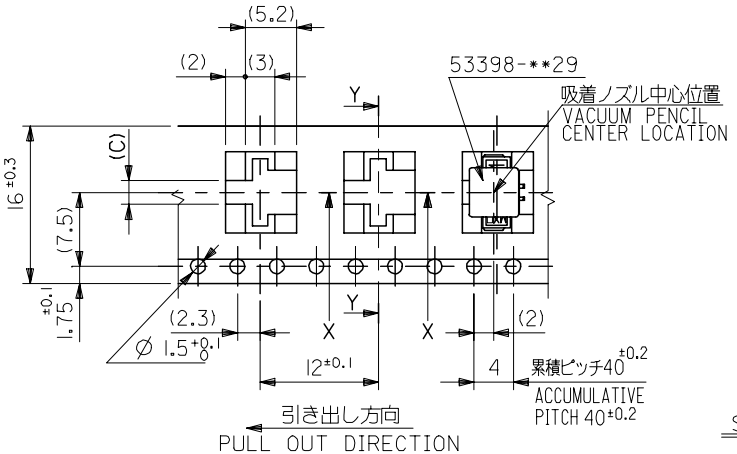
DO NOT SCALE DRAWING

SD-53398-034.S02

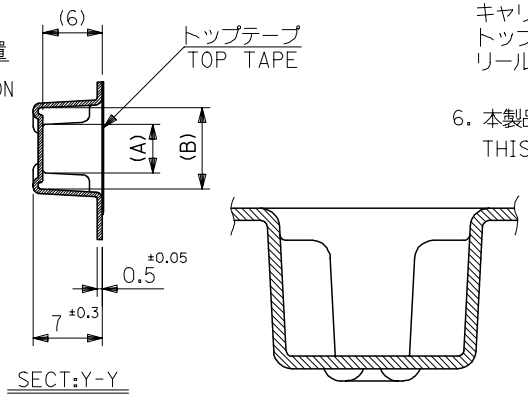
EN-02J(097) MXJ-54



DETAIL "F"

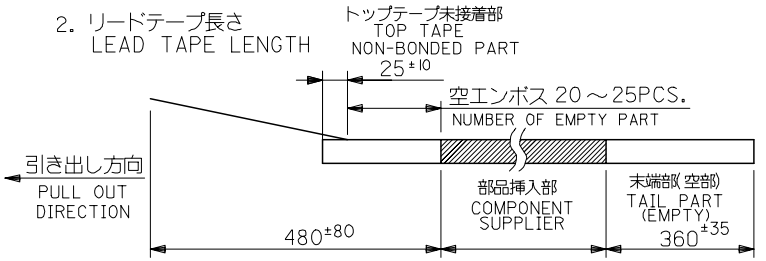


16幅テープ
(TAPE WIDTH:16)



NOTES

1. 梱包数量：1000個／リール
   NUMBER OF CONNECTOR:1000PCS/REEL
2. リードテープ長さ
   LEAD TAPE LENGTH



3. トップテープの剥離強度：0.6±0.35N(60±35gf)（剥離方向は下図参照）
   PEELING OFF FORCE OF TOP TAPE：0.6±0.35N(60±35gf)
   (PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)
   ＜剥離速度： 300mm/min（参考）＞
   PEELING SPEED:300mm/min. (REFERENCE)



4. 53398-**29 の詳細寸法については図面 SD-53398-034 を参照下さい。
   RE DETAILED DIMENSIONS, SEE SD-53398-034.
5. 材料 (MATERIAL)
   キャリアテープ (CARRIER TAPE):ポリプロピレン(POLYPROPYLENE)
   トップテープ (TOP TAPE): PET ,PE ,PEF
   リール (REEL)：ポリスチレン (PS) ＜リサイクル材含む＞
   POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
6. 本製品は 53398-**80 の鉛フリー品である。
   THIS PRODUCT IS LEAD FREE OF 53398-**80.

キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	MATERIAL NO.	CIRCUITS
32	33.4	14.95	20.75	17.05	53398-1267	12
24	25.4	9.95	15.75	12.05	53398-0867	8
		8.7	14.5	10.8	53398-0767	7
		7.45	13.25	9.55	53398-0667	6
		6.2	12	8.3	53398-0567	5
		4.95	10.75	7.05	53398-0467	4
		3.7	9.5	5.8	53398-0367	3
16	17.4	2.45	8.25	4.55	53398-0267	2

REVISED
EC NO:
DRWN:MERIGUCH 2004/07/28
CHKD:K.ASAKAW 2004/07/28
APPR:SICHIKAW 2004/07/30
DESCRIPTION
REV
A

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY	SCALE: ---	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION

DRAWN BY: J.SASAMO	DATE: 2004/7/22
CHECKED BY: K.TOJO	DATE: 2004/7/22
APPROVED BY: N.UKITA	DATE: 2004/7/22
MATERIAL NO.: SEE CHART	

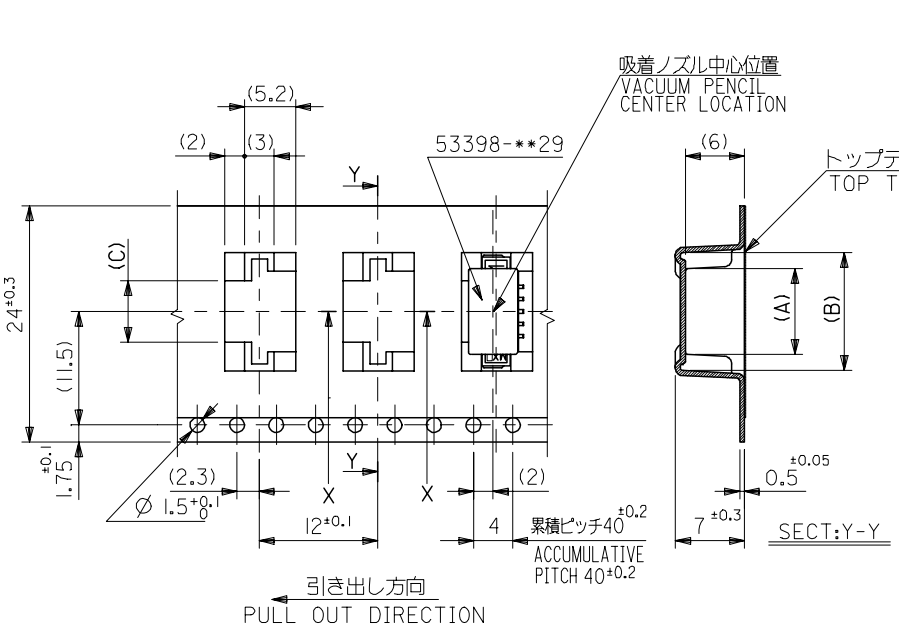
TITLE: EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-

molex MOLEX INCORPORATED

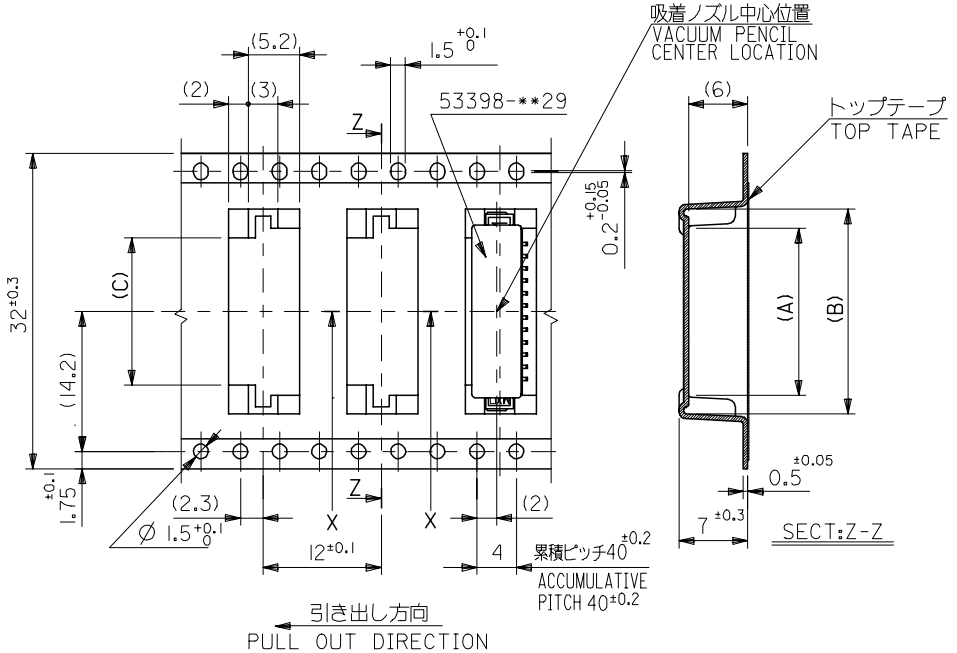
DOCUMENT NO.: SD-53398-035
SHEET NO.: 1 OF 2

SIZE A3

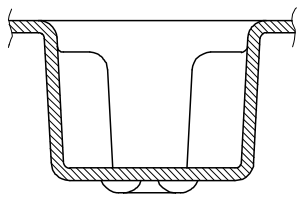
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24幅テープ
(TAPE WIDTH:24)



32幅テープ
(TAPE WIDTH:32)



SECT:X-X

REVISED				REV
EC NO:	DRWN:MERIGUCH	CHKD:K.ASAKAW	APPR:SICHIKAW	DESCRIPTION
	2004/07/28	2004/07/28	2004/07/30	
A				

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY	SCALE: ---	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: J.SASAMO	DATE: 2004/7/22	TITLE: EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-	
CHECKED BY: K.TOJO	DATE: 2004/7/22		
APPROVED BY: N.UKITA	DATE: 2004/7/22	molex MOLEX INCORPORATED	
MATERIAL NO.: SEE CHART		DOCUMENT NO.: SD-53398-035	SHEET NO.: 2 OF 2
SIZE: A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		